

HPX thermal conductive paste

The HPX thermal conductive paste with a heat transfer coefficient of >2.8 W/mK, which does not conduct electric current. It is necessary for the proper operation of all kinds of temperature sensors. The low thermal impedance of the paste makes it possible to maintain constant performance at temperatures from -30 to 300°C .

Application:

Units modules with a high heat transfer coefficient

Cooling devices on terminal boards and frames

- Flash memory drives and high-speed drives
- Motor control systems (automotive industry)
- Hard disc and DVD drives
- Power transducers
- High-power LED diodes
- Notebooks and office computers
- Network communication devices
- Household appliances, electronic and electrical components
- Air conditioning devices

Physicochemical properties:

Parameters	UoM	Result
colour	-	grey
thermal conductivity	W/mK	>2.8
thermal impedance	$^{\circ}\text{C in}2/\text{W}$	< 0.095
specific weight	g/cm^3	>2.5
evaporation	-	0.001
ingress	-	0.05
dielectric constant	-	5.1
Viscosity	-	does not flow
thixotropic index	-	$380+/-10$
resistance to temperature	$^{\circ}\text{C}$	$-50-340^{\circ}\text{C}$
operating temperature	$^{\circ}\text{C}$	$-30-300$

Packagings:

Volume	Collective packaging	Item Code
60 g (cartridge)	5	ART.AGT-126
100 g (jar)	6	ART.AGT-128
1000 g (container)	1	ART.AGT-114

Warehousing:

Store in a well-ventilated, cool and dry place. Keep containers tightly closed when not in use. Protect against sunlight exposure.

Data contained in this document are consistent with the current state of our knowledge. They describe typical product properties and applications. However, it is up to the user to examine the suitability of this product for specific applications. We deny liability for the obtained results on the grounds that application conditions lie beyond our control.